

Title (en)

BGA CONNECTOR WITH HEAT ACTIVATED CONNECTION AND DISCONNECTION MEANS

Title (de)

BGA-VERBINDER MIT WÄRMEAKTIVIERTEN MITTELN ZUM VERBINDEN UND LÖSEN

Title (fr)

CONNECTEUR BGA MUNI DE MOYENS DE CONNEXION ET DE DECONNEXION ACTIVES A CHAUD

Publication

**EP 0970522 A1 20000112 (EN)**

Application

**EP 98964132 A 19981218**

Priority

- JP 36512597 A 19971219
- US 9827066 W 19981218

Abstract (en)

[origin: WO9933109A1] An improved connector assembly (1) particularly useful for testing semiconductor devices of ball grid array ("BGA") structure (10) with a plurality of solder balls (11) formed on the surface thereof. The balls (11) are placed into contact with opposing conductive portions (3a) of the connector assembly. A heat generating member (7), such as a wire, is disposed proximate to the connector assembly conductive portions (3a) and may be selectively energized to generate heat to partially melt the solder balls (11). Reliable connections are effected in this manner.

IPC 1-7

**H01L 23/498; H05K 3/34**

IPC 8 full level

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**G01R 1/073** (2006.01); **G01R 31/28** (2006.01); **H05K 1/14** (2006.01); **H05K 1/16** (2006.01)

CPC (source: EP)

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